Materials Declaration

Package	TSSOP
Body Size	4.4 mm
LeadCount	16
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87.7	2.94 E-02	501312
Resin	11.0	3.70 E-03	63022
Brominated resin	0.6	1.85 E-04	3151
Sb2O3	0.4	1.34 E-04	2292
Carbon Black	0.3	1.01 E-04	1719
Subtotal		3.35 E-02	571495

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.80 E-02	307363
Ni	3.00	6.08 E-04	10364
Si	0.65	1.37 E-04	2332
Mg	0.15	3.42 E-05	583
Subtotal		1.88 E-02	320642

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.90 E-04	3239

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.26 E-03	21476

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	5.60 E-04	9545

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.99 E-03	50883

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	1.05 E-03	17967
Resin	20	2.04 E-04	3477
Aromatic Amine	5	7.48 E-05	1275
Subtotal		1.33 E-03	22719

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cd	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Hg	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cr+6	None Detected	EPA Method 3060A. Draft IEC62321. UV-VIS
PBB	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.
PBDE	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cd	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Hg	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cr+6	None Detected	EPA Method 3060A. Draft IEC62321. UV-VIS
PBB	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.
PBDE	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.

Package Totals

Weight (g)	PPM
5.87 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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Materials Declaration

Package	TSSOP
Body Size	4.4 mm
LeadCount	16
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87.7	2.94 E-02	500543
Resin	11.0	3.70 E-03	62925
Brominated resin	0.6	1.85 E-04	3146
Sb2O3	0.4	1.34 E-04	2288
Carbon Black	0.3	1.01 E-04	1716
Subtotal		3.35 E-02	570619

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.80 E-02	306891
Ni	3.00	6.08 E-04	10348
Si	0.65	1.37 E-04	2328
Mg	0.15	3.42 E-05	582
Subtotal		1.88 E-02	320150

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.90 E-04	3234

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.15 E-03	19531
Pb	15	2.03 E-04	3447
Subtotal		1.35 E-03	22977

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	5.60 E-04	9530

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.99 E-03	50805

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	1.05 E-03	17939
Resin	20	2.04 E-04	3472
Aromatic Amine	5	7.48 E-05	1273
Subtotal		1.33 E-03	22685

Package Totals

Weight (g)	PPM
5.88 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cd	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Hg	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cr+6	None Detected	EPA Method 3060A. Draft IEC62321. UV-VIS
PBB	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.
PBDE	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cd	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Hg	None Detected	EPA Method 3052. Draft IEC62321. ICP-OES.
Cr+6	None Detected	EPA Method 3060A. Draft IEC62321. UV-VIS
PBB	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.
PBDE	None Detected	EPA Method 3540C. Draft IEC62321. GC/MS-D.

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